

STB24N65M2, STF24N65M2, STP24N65M2

N-channel 650 V, 0.185 Ω typ., 16 A MDmesh M2
Power MOSFET in D2PAK, TO-220FP and TO-220 packages

Datasheet - production data

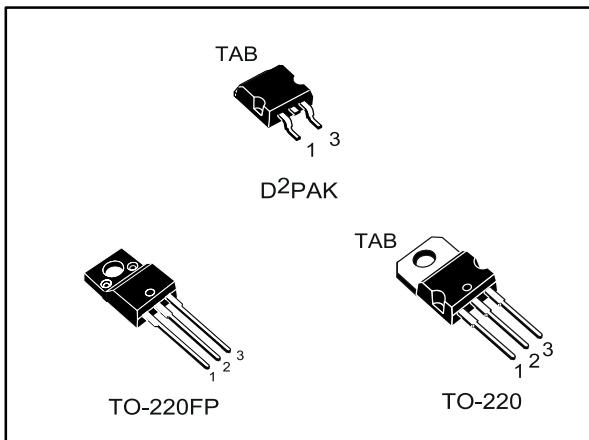
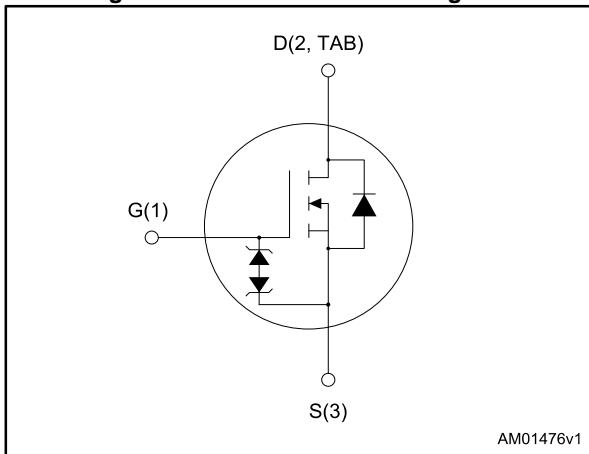


Figure 1: Internal schematic diagram



Features

Order codes	V _{DS}	R _{DS(on)} max	I _D
STB24N65M2	650 V	0.23 Ω	16 A
STF24N65M2			
STP24N65M2			

- Extremely low gate charge
- Excellent output capacitance (C_{oss}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs developed using MDmesh™ M2 technology. Thanks to their strip layout and improved vertical structure, the devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high efficiency converters.

Table 1: Device summary

Order codes	Marking	Package	Packaging
STB24N65M2	24N65M2	D2PAK	Tape and reel
STF24N65M2		TO-220FP	Tube
STP24N65M2		TO-220	

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves).....	6
3	Test circuits	9
4	Package mechanical data	10
4.1	D2PAK package information	10
4.2	TO-220FP package information	13
4.3	TO-220 type A package information.....	15
5	Packaging mechanical data.....	17
6	Revision history	19

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value		Unit
		D ² PAK TO-220	TO-220FP	
V _{GS}	Gate-source voltage	± 25		V
I _D	Drain current (continuous) at T _C = 25 °C	16	16 ⁽¹⁾	A
I _D	Drain current (continuous) at T _C = 100 °C	10	10 ⁽¹⁾	A
I _{DM} ⁽²⁾	Drain current (pulsed)	64	64 ⁽¹⁾	A
P _{TOT}	Total dissipation at T _C = 25 °C	150	30	W
dv/dt ⁽³⁾	Peak diode recovery voltage slope	15		V/ns
dv/dt ⁽⁴⁾	MOSFET dv/dt ruggedness	50		V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T _C = 25 °C)		2500	V
T _{stg}	Storage temperature	- 55 to 150		°C
T _j	Max. operating junction temperature			

Notes:

⁽¹⁾Limited by maximum junction temperature.

⁽²⁾Pulse width limited by safe operating area.

⁽³⁾I_{SD} ≤ 16 A, di/dt ≤ 400 A/μs; V_{DS(peak)} < V_{(BR)DSS}, V_{DD} = 80% V_{(BR)DSS}.

⁽⁴⁾V_{DS} ≤ 520 V

Table 3: Thermal data

Symbol	Parameter	Value			Unit
		D ² PAK	TO-220	TO-220FP	
R _{thj-case}	Thermal resistance junction-case max	0.83		4.2	°C/W
R _{thj-pcb}	Thermal resistance junction-pcb max ⁽¹⁾	30			°C/W
R _{thj-amb}	Thermal resistance junction-ambient max			62.5	°C/W

Notes:

⁽¹⁾When mounted on 1 inch² FR-4, 2 Oz copper board.

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T _{jmax})	2.2	A
E _{AS}	Single pulse avalanche energy (starting T _j =25°C, I _D = I _{AR} ; V _{DD} =50V)	650	mJ

2 Electrical characteristics

($T_c = 25^\circ\text{C}$ unless otherwise specified)

Table 5: On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	650			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = 650 \text{ V}$			1	μA
		$V_{DS} = 650 \text{ V}, T_c=125^\circ\text{C}$			100	μA
I_{GS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 25 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		0.185	0.23	Ω

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	1060	-	pF
C_{oss}	Output capacitance		-	47.5	-	pF
C_{rss}	Reverse transfer capacitance		-	1.65	-	pF
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 520 \text{ V}, V_{GS} = 0$	-	229	-	pF
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0$	-	7	-	Ω
Q_g	Total gate charge	$V_{DD} = 520 \text{ V}, I_D = 16 \text{ A}, V_{GS} = 10 \text{ V}$	-	29	-	nC
Q_{gs}	Gate-source charge		-	3.8	-	nC
Q_{gd}	Gate-drain charge		-	14	-	nC

Notes:

⁽¹⁾ $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 325 \text{ V}, I_D = 8 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	10	-	ns
t_r	Rise time		-	9.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	68	-	ns
t_f	Fall time		-	25.5	-	ns

Table 8: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		16	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		64	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 16 \text{ A}, V_{GS} = 0$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 16 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$	-	350		ns
Q_{rr}	Reverse recovery charge		-	4.5		μC
I_{RRM}	Reverse recovery current		-	26		A
t_{rr}	Reverse recovery time	$I_{SD} = 16 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	-	496		ns
Q_{rr}	Reverse recovery charge		-	6.5		μC
I_{RRM}	Reverse recovery current		-	25.5		A

Notes:

(1)Pulse width limited by safe operating area.

(2)Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1

Electrical characteristics (curves)

Figure 2: Safe operating area for D2PAK and TO-220

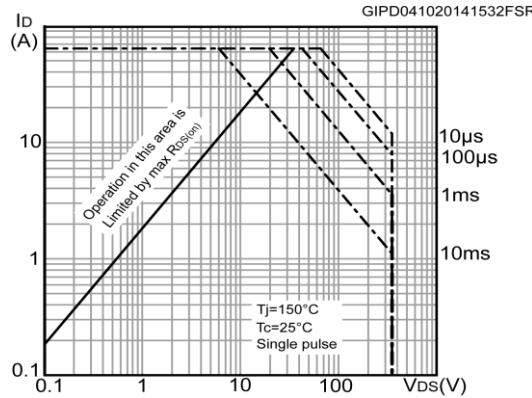


Figure 3: Thermal impedance for D2PAK and TO-220

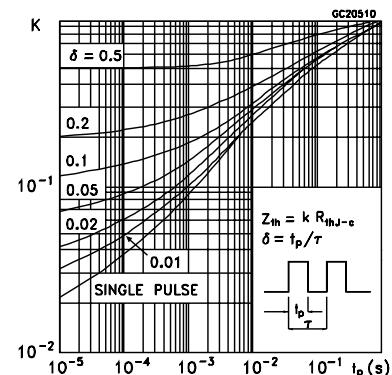


Figure 4: Safe operating area for TO-220FP

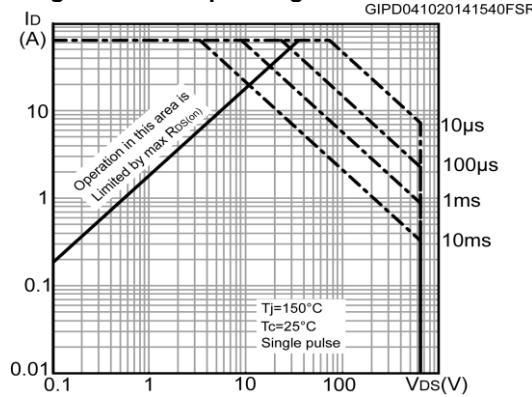


Figure 5: Thermal impedance for TO-220FP

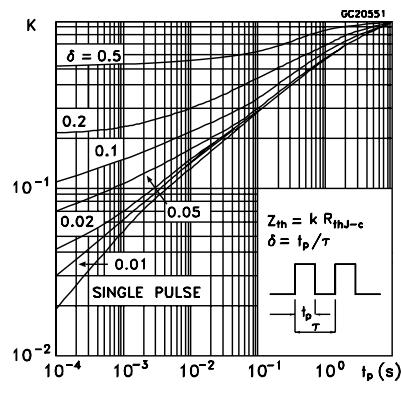


Figure 6: Output characteristics

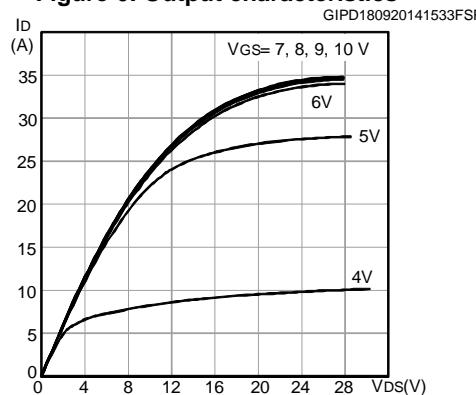


Figure 7: Transfer characteristics

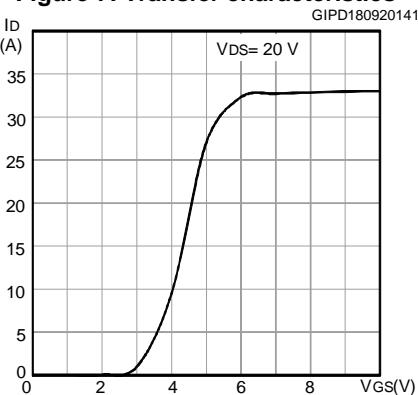
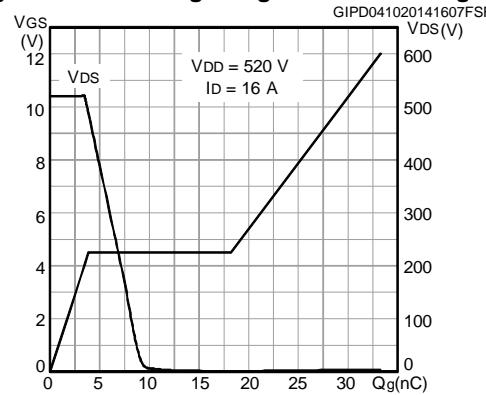
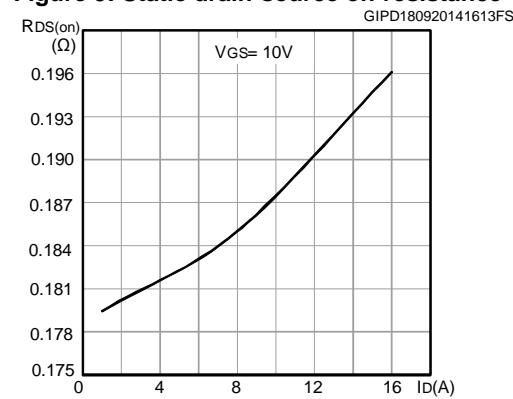
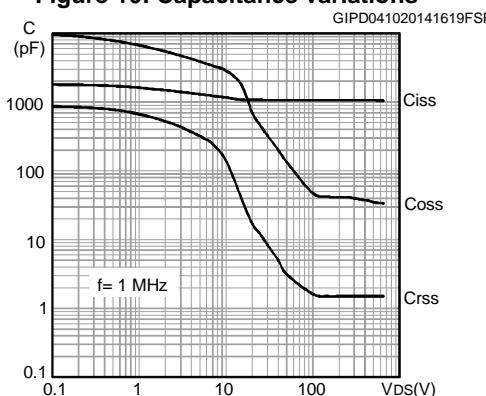
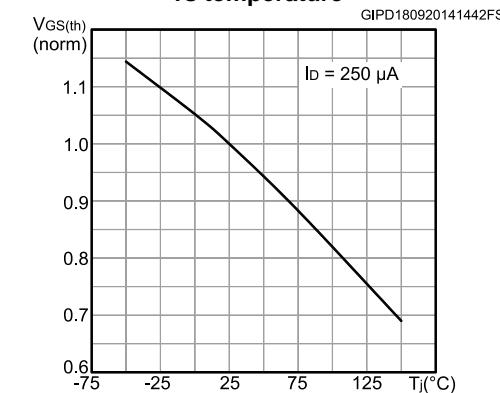
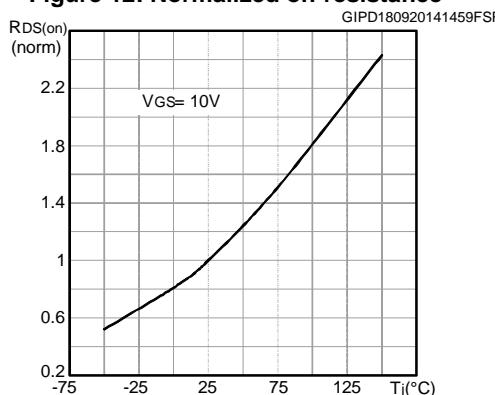
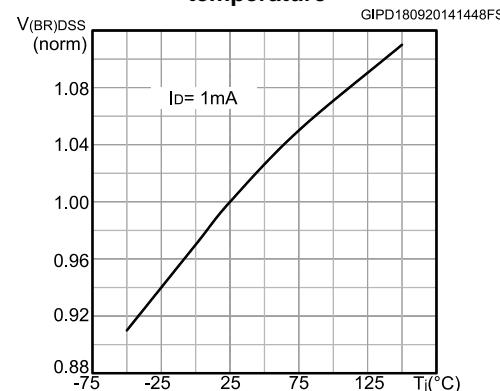


Figure 8: Gate charge vs gate-source voltage**Figure 9: Static drain-source on-resistance****Figure 10: Capacitance variations****Figure 11: Normalized gate threshold voltage vs temperature****Figure 12: Normalized on-resistance****Figure 13: Normalized V(BR)DSS vs temperature**

Electrical characteristics

STB24N65M2, STF24N65M2, STP24N65M2

Figure 14: Source-drain diode forward characteristics

GIPD041020141624FSF

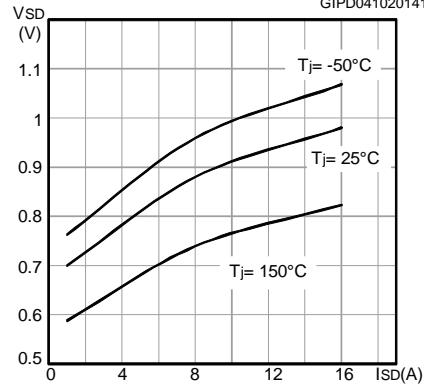
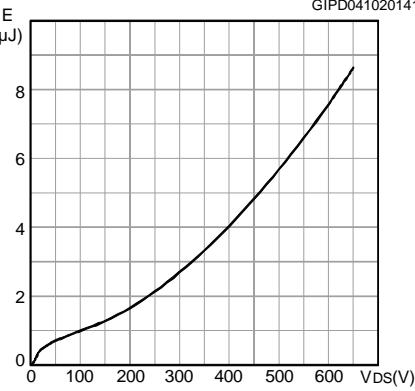


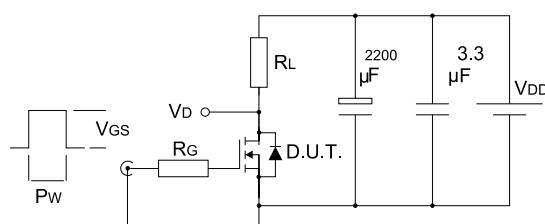
Figure 15: Output capacitance stored energy

GIPD041020141629FSF



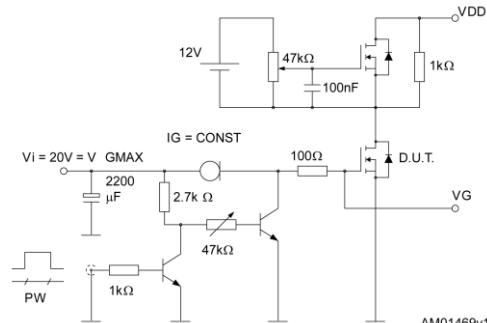
3 Test circuits

Figure 16: Switching times test circuit for resistive load



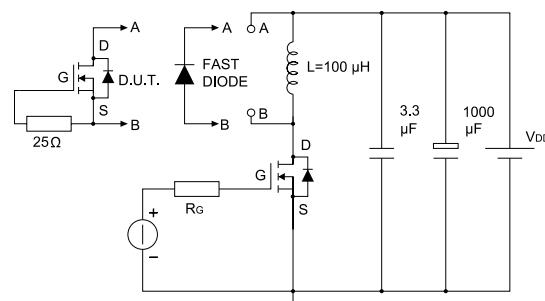
AM01468v1

Figure 17: Gate charge test circuit



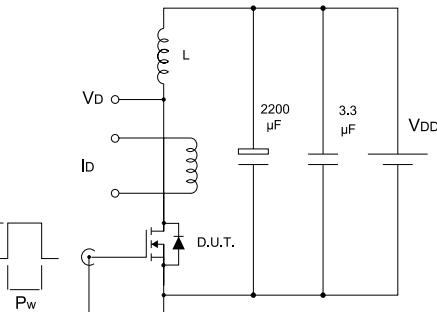
AM01469v1

Figure 18: Test circuit for inductive load switching and diode recovery times



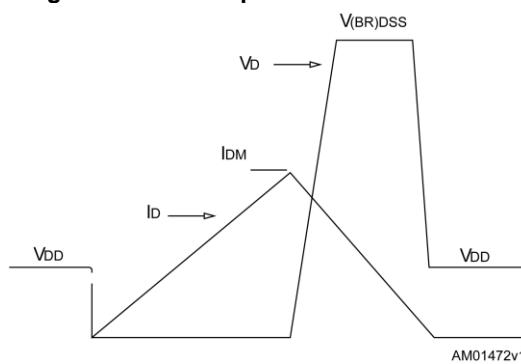
AM01470v1

Figure 19: Unclamped inductive load test circuit



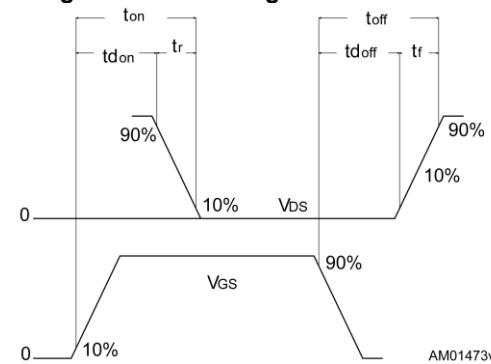
AM01471v1

Figure 20: Unclamped inductive waveform



AM01472v1

Figure 21: Switching time waveform



AM01473v1

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 D2PAK package information

Figure 22: D²PAK (TO-263) drawing

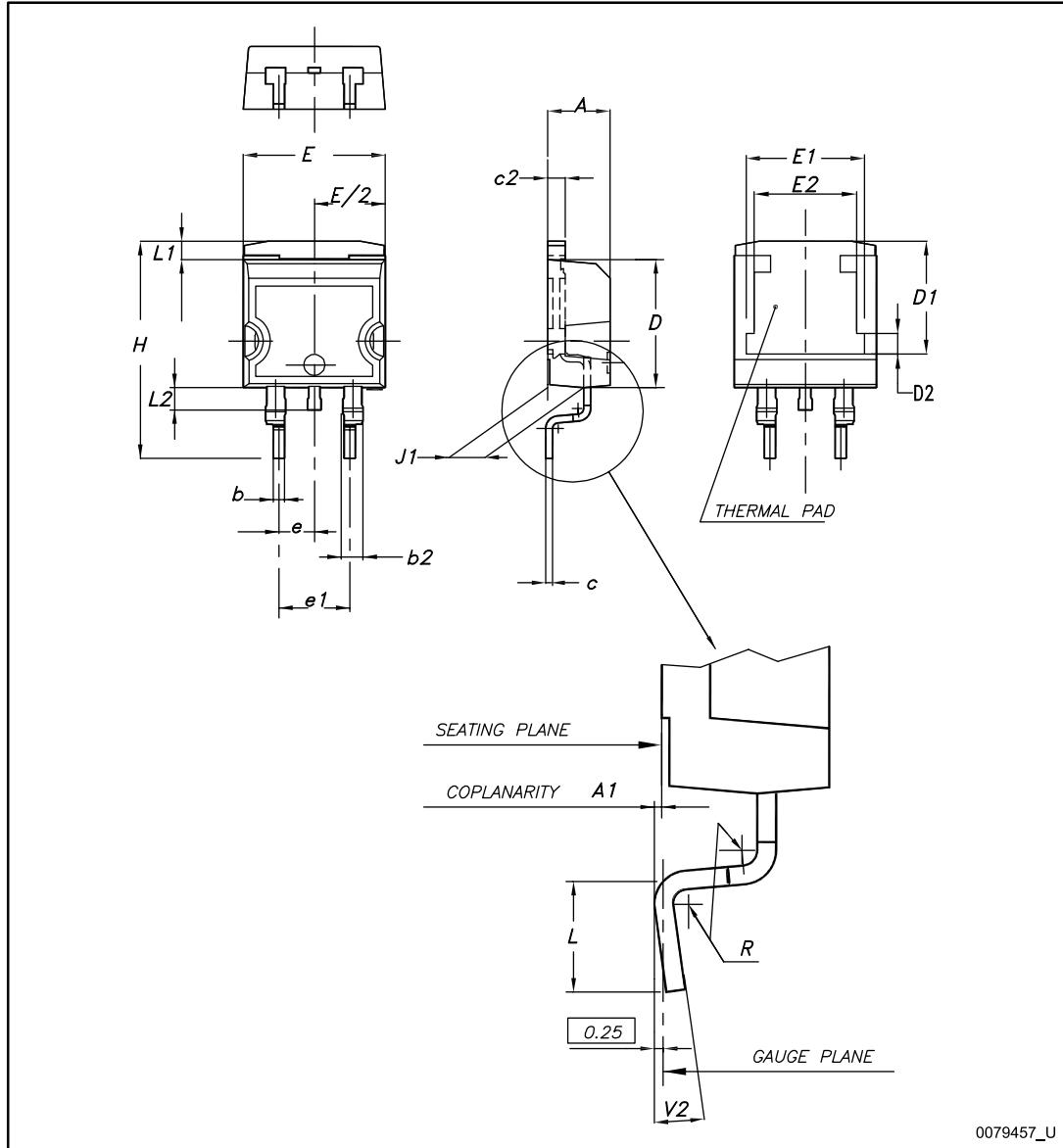
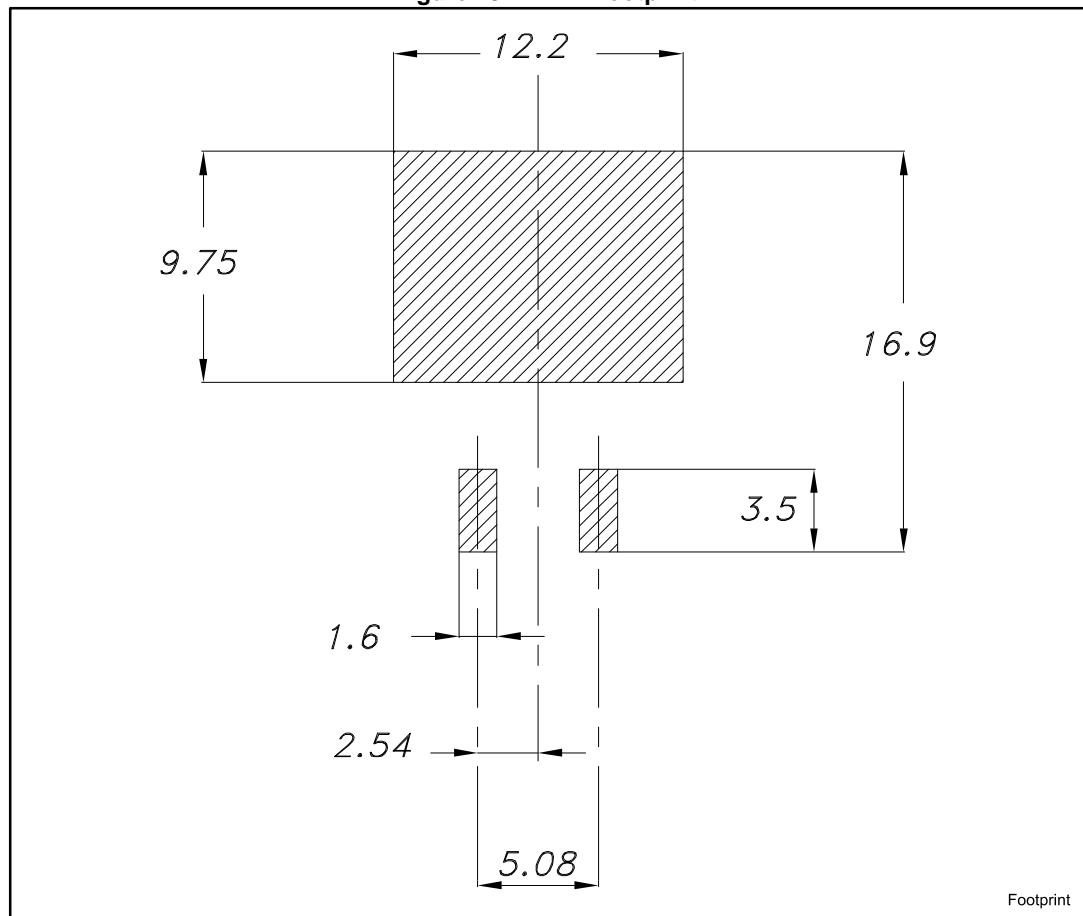


Table 9: D²PAK (TO-263) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 23: D²PAK footprint

All the dimensions are in millimeters.

Footprint

4.2 TO-220FP package information

Figure 24: TO-220FP package outline

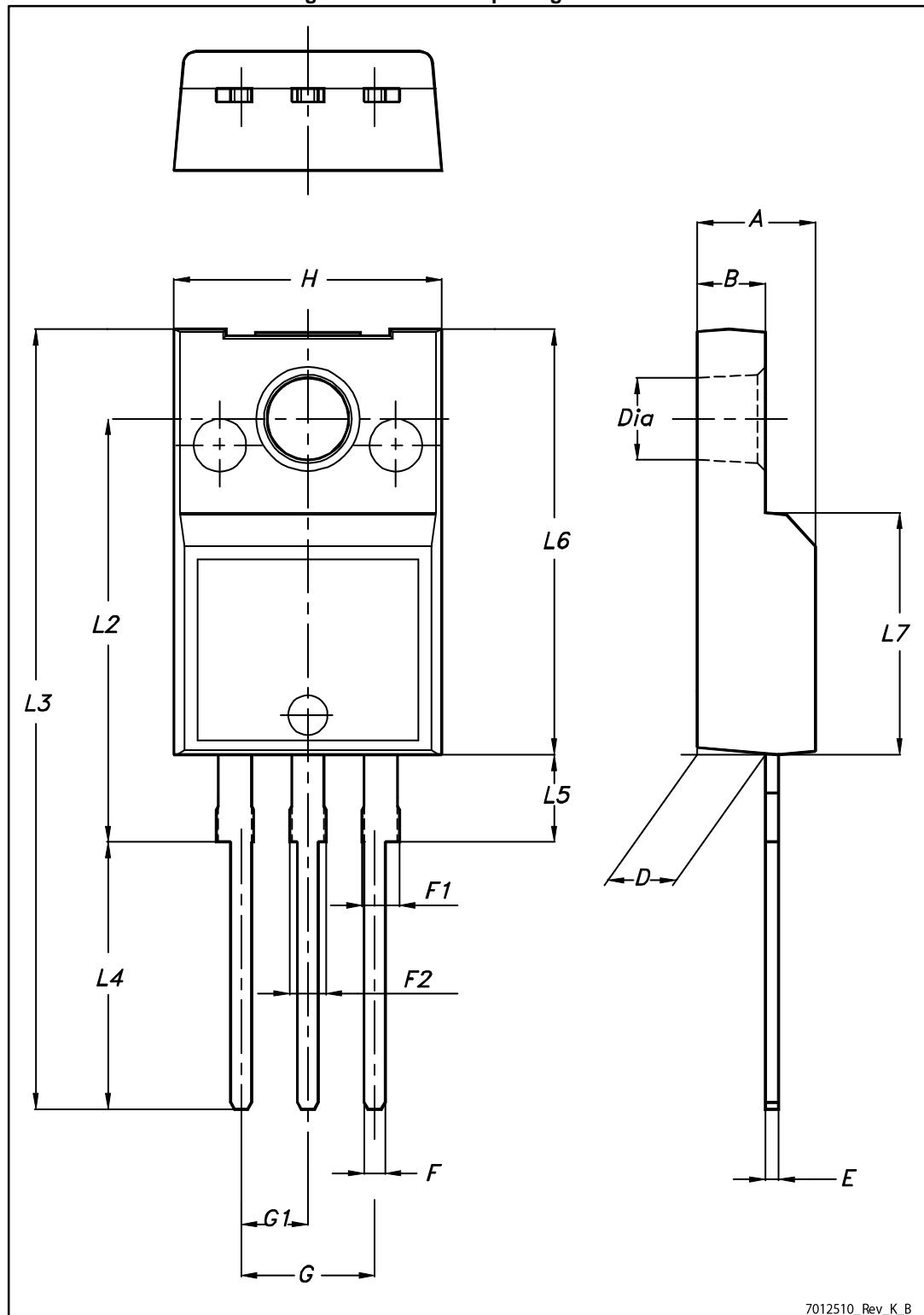


Table 10: TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

4.3 TO-220 type A package information

Figure 25: TO-220 type A package outline

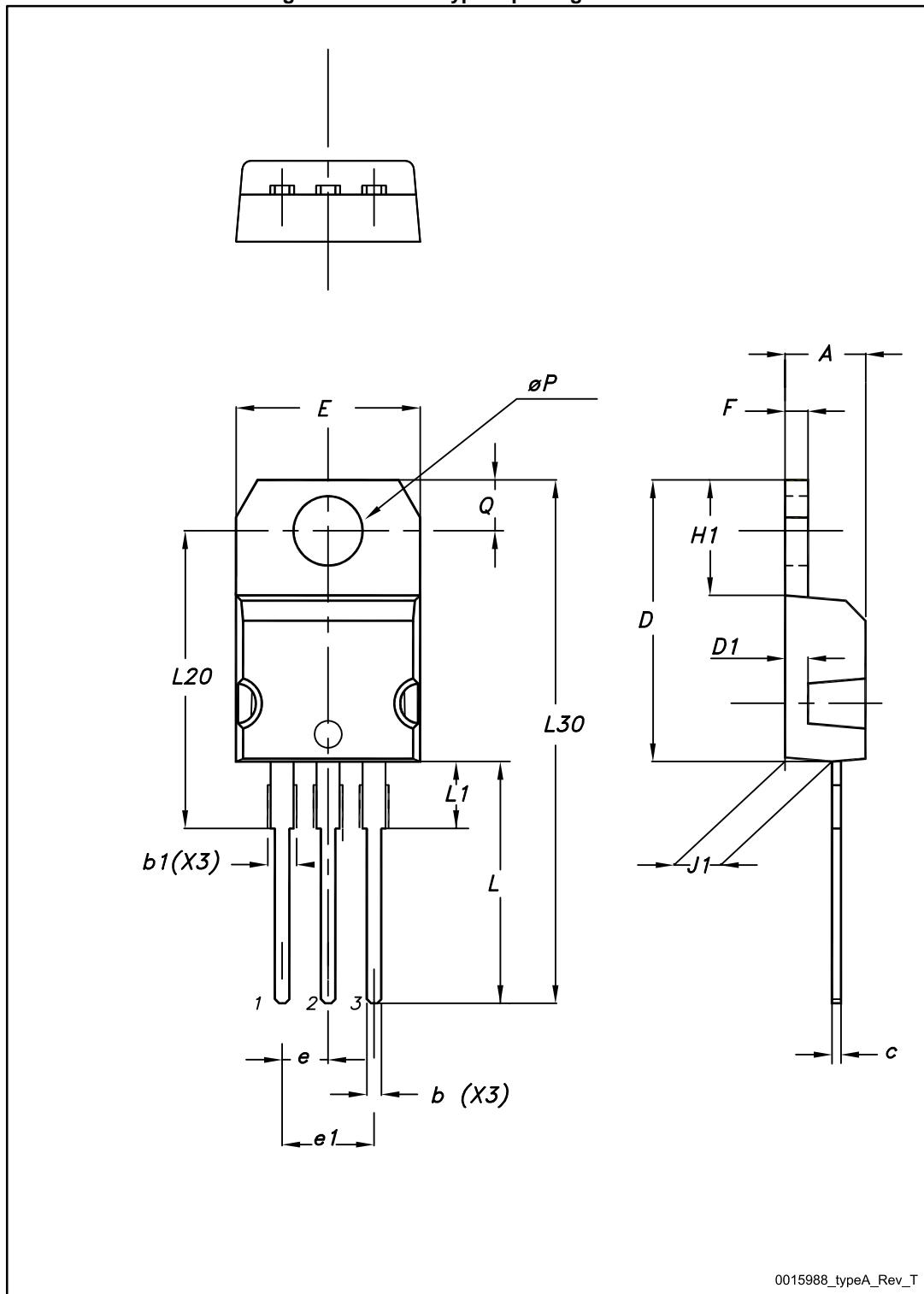


Table 11: TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

5 Packaging mechanical data

Figure 26: Tape

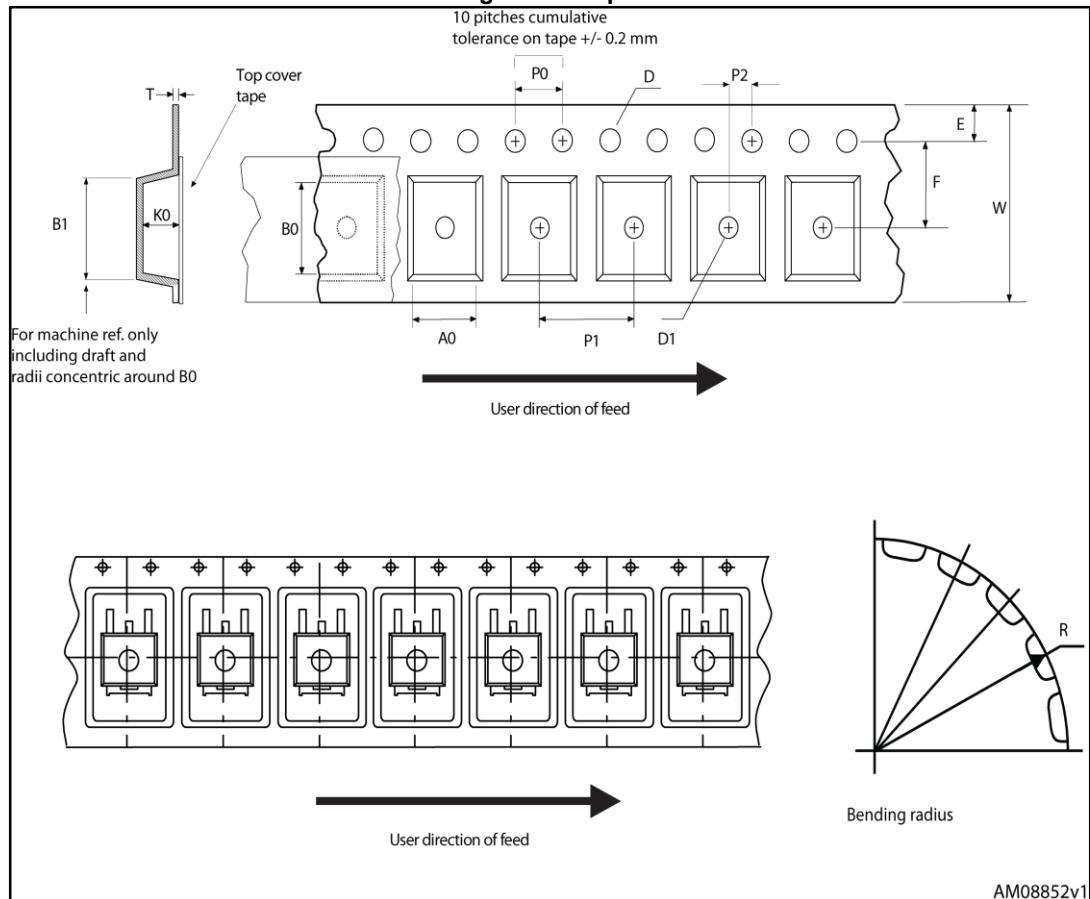


Figure 27: Reel

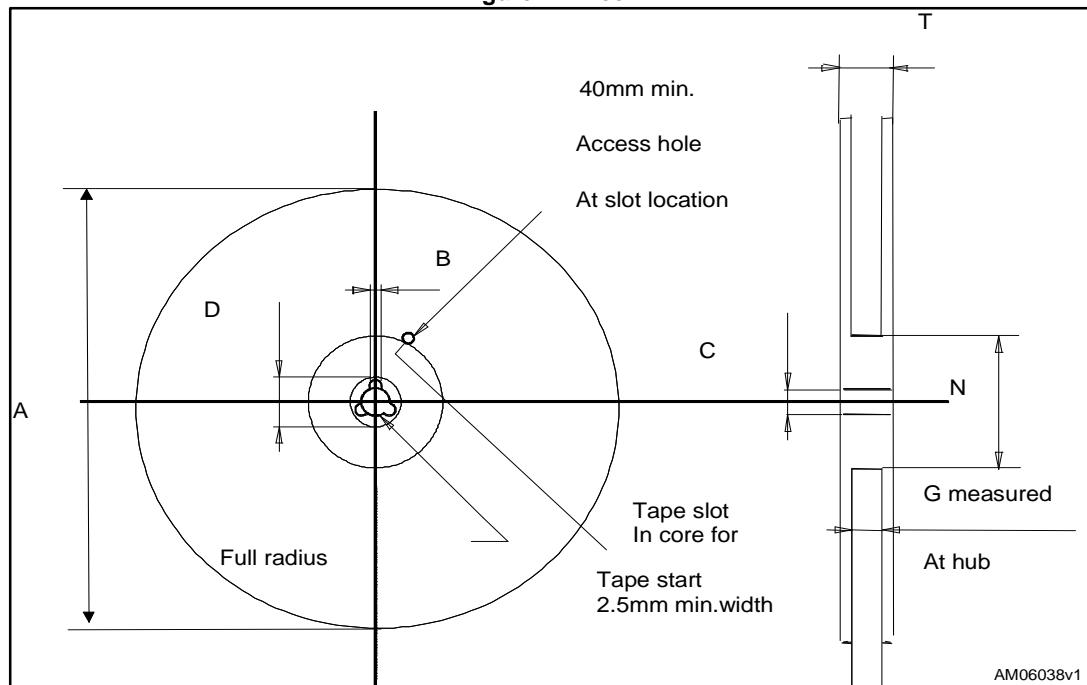


Table 12: D²PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

6 Revision history

Table 13: Document revision history

Date	Revision	Changes
09-Jun-2014	1	First release.
11-Nov-2014	2	Document status promoted from preliminary to production data.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2014 STMicroelectronics – All rights reserved

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by STMicroelectronics manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [IRFD120](#) [JANTX2N5237](#) [2N7000](#) [FCA20N60_F109](#) [FDZ595PZ](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#)
[TPCC8103,L1Q\(CM](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [SSM6J414TU,LF\(T](#) [751625C](#)
[IPS70R2K0CEAKMA1](#) [BUK954R8-60E](#) [DMN3404LQ-7](#) [NTE6400](#) [SQJ402EP-T1-GE3](#) [2SK2614\(TE16L1,Q\)](#) [2N7002KW-FAI](#)
[DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [ECH8691-TL-W](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE221](#) [NTE2384](#)
[NTE2903](#) [NTE2941](#) [NTE2945](#) [NTE2946](#) [NTE2960](#) [NTE2967](#) [NTE2969](#) [NTE2976](#) [NTE455](#) [NTE6400A](#) [NTE2910](#) [NTE2916](#) [NTE2956](#)
[NTE2911](#) [US6M2GTR](#) [TK10A80W,S4X\(S](#) [SSM6P69NU,LF](#)